

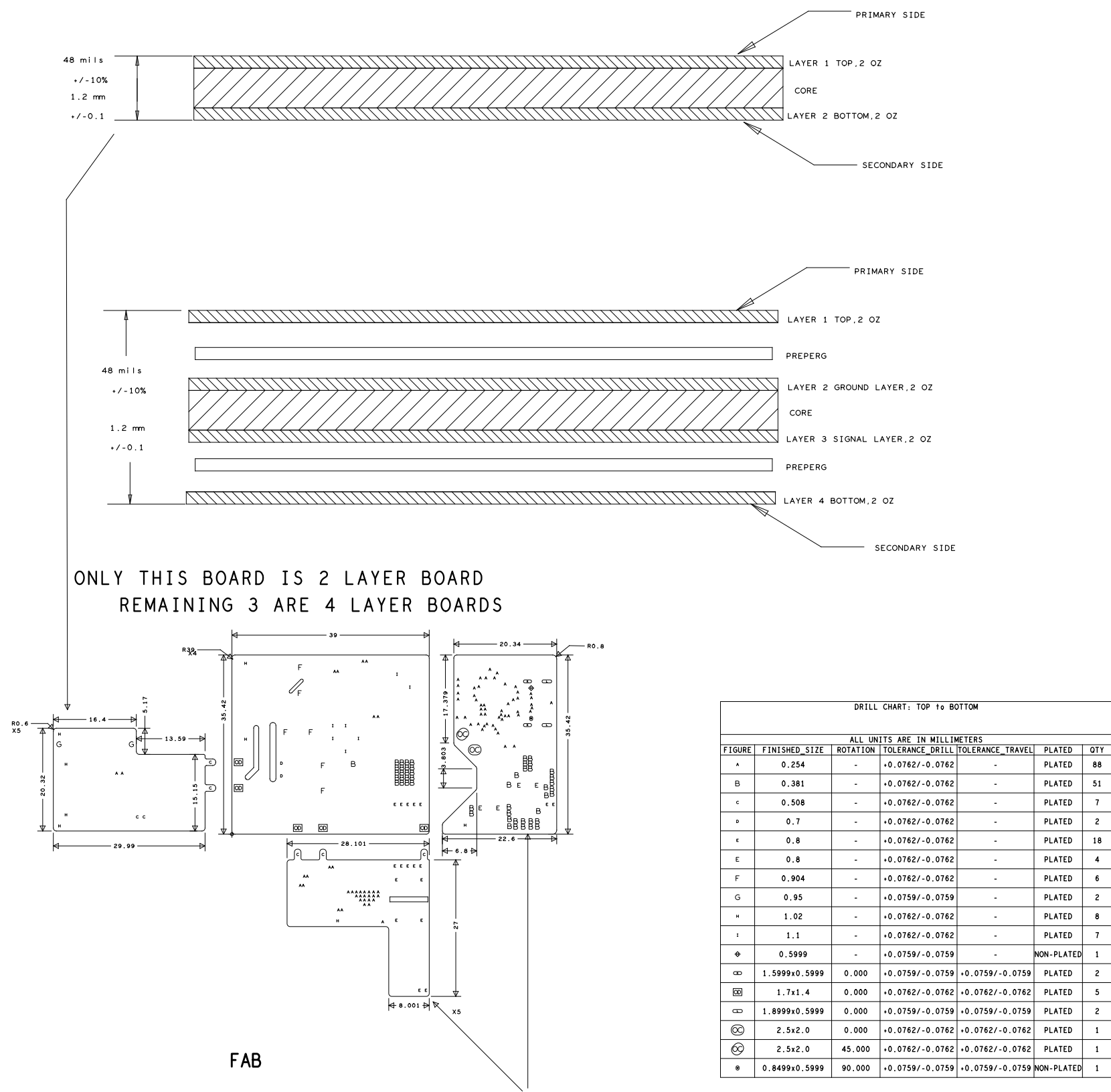
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	INITIAL RELEASE	02/09/20	RAAH
2	REVISION 2	04/01/21	HSUB
3	REVISION 3	12/03/21	HSUB


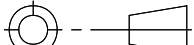
NOTES: (UNLESS OTHERWISE SPECIFIED)

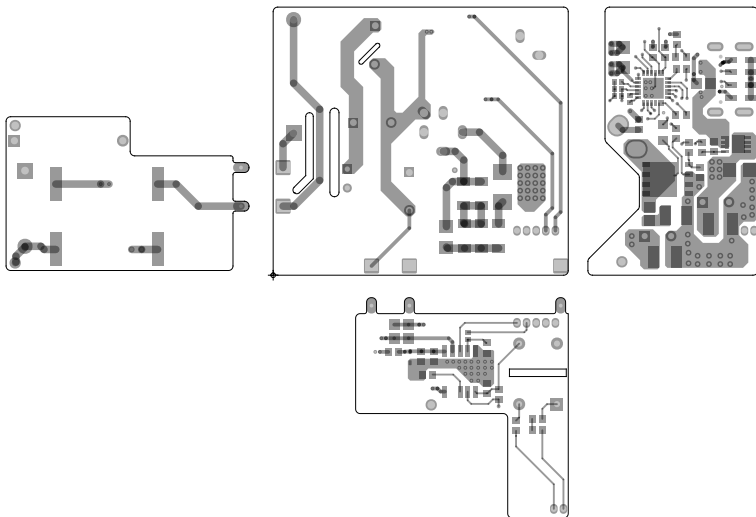
1. RoHS COMPLIANT MATERIALS (COPPER, NICKEL, GOLD, SOLDER) REQUIRED.
2. MATERIAL:
 - A. FR4 OR EQUIVALENT MATERIAL(HIGH ELECTRONIC RELIABILITY) MUST CONFIRM TO UL94V-0
 - B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
 - C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
 - A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES $\pm .003$ to 1. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
 - B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:

COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
 - A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
 - B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPLIANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
 - A. SOLDERMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR *BLUE**
7. FINISH:
 - A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).
 - B. NICKEL THICKNESS: 100-200 MICROINCHES.
 - C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.

FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
 - A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
 - B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE $\pm 10\%$ UNLESS OTHERWISE SPECIFIED.
12. ENSURE ALL THE VIA HOLES ARE FILLED WITH SOLDER MASK TO ENSURE GOOD QUALITY OF SILK SCREEN PRINT.
13. CARE MUST BE TAKEN TO AVOID OVER ETCHING OF COPPER ON PADS.
14. THIS IS HIGH VOLTAGE BOARD. SO DON'T ADD THIEVING COPPER IN VOID AREA FOR COPPER BALANCE.
15. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH CTI STANDARD OF $400 < CTI < 600$

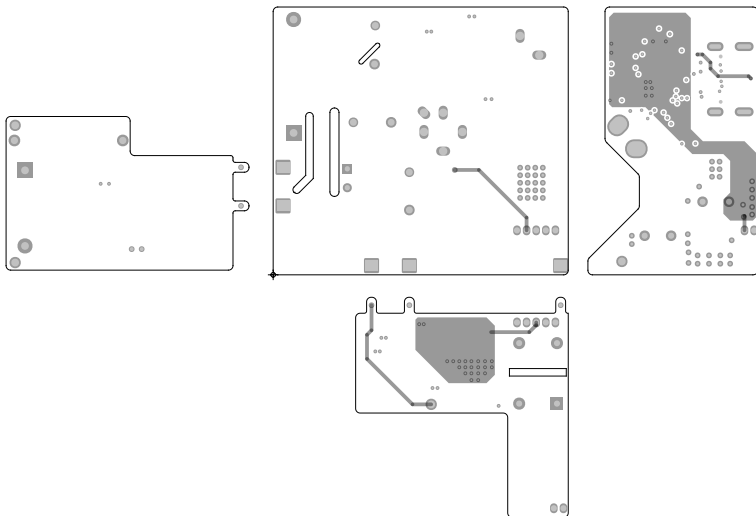


UNLESS OTHERWISE SPECIFIED		SIGNATURES		DATE		<div></div> <div>198 CHAMPION COURT SAN JOSE, CA 95134 (408) 943-2600</div>	
DIMENSIONS ARE IN INCHES		DRAWN :	SAND	12/03/21		FABRICATION DRAWING CY-SD1124A PAG1S+PAG1P 45W SOLUTION DEMO BOARD	
TOLERANCES ON; ANGLES +/- 2°		CHECKED :	HSUB	12/03/21			
2 PL DECIMALS +/- .010		ENGRG :	HSUB	12/03/21			
3 PL DECIMALS +/- .005		ISSUED					
THIRD ANGLE PROJECTIONS 							
CYPRESS PROPRIETARY							
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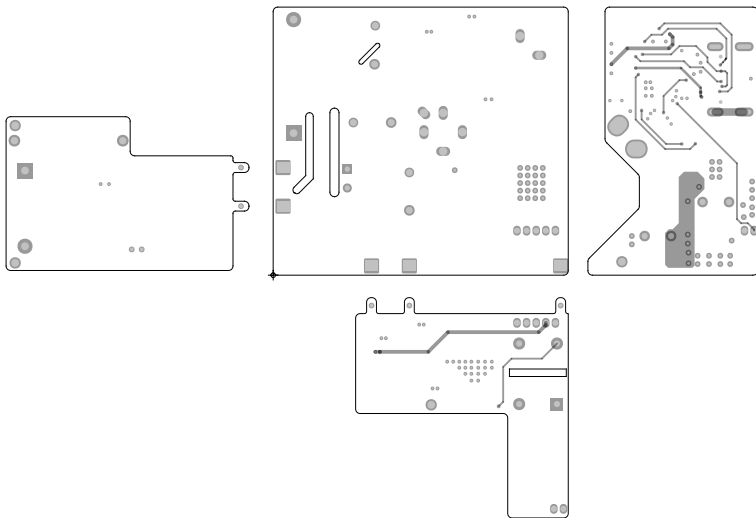
CY-SD1124A REV03 PRIMARY SIDE

ART FILM - 2#INNER1



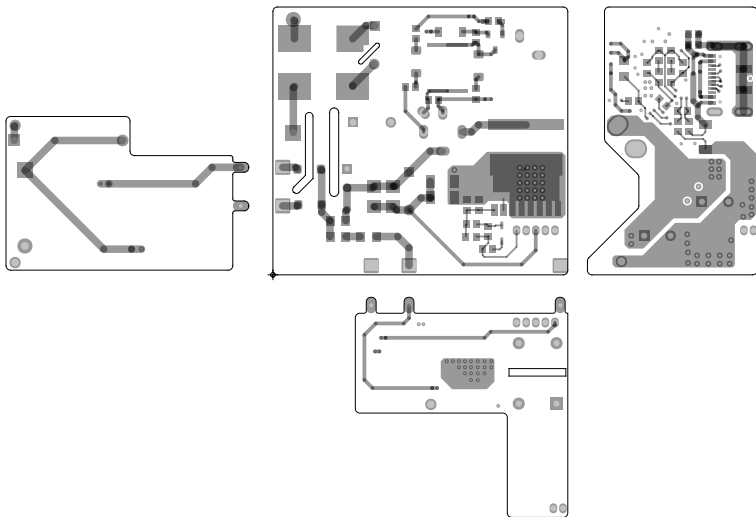
CY-SD1124A REV03 INNER LAYER1

ART FILM - 2#INNER1



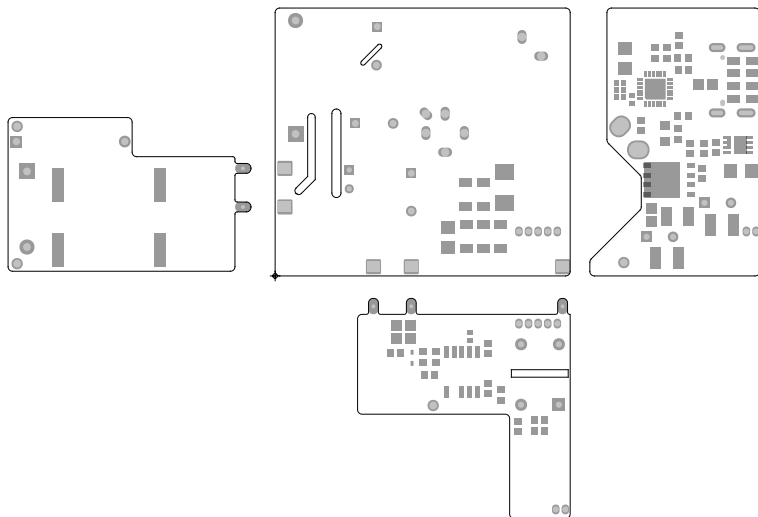
CY-SD1124A REV03 INNER LAYER2

ART FILM - 4#BOT

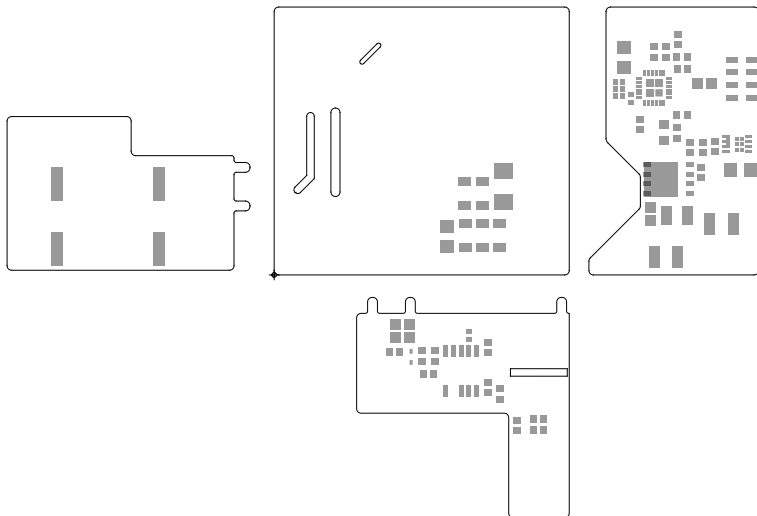


CY-2D11S4A REV03 SECONDARY SIDE

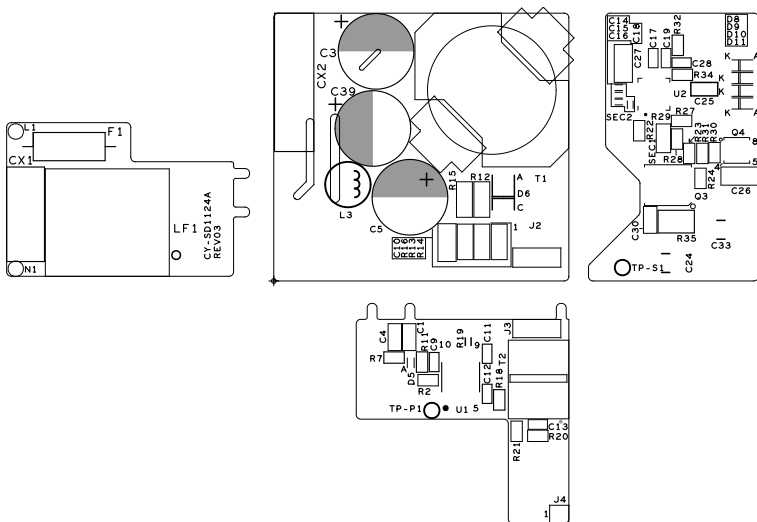
ART FILM - 4#BOT



CY-SD1124A REV03 SOLDER MASK PRIMARY SIDE

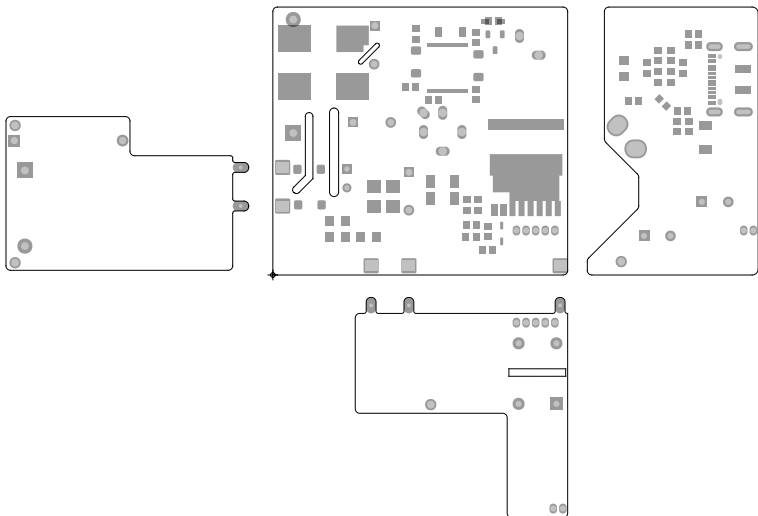


CY-SD1124A REV03 PRIMARY SOLDERPASTE



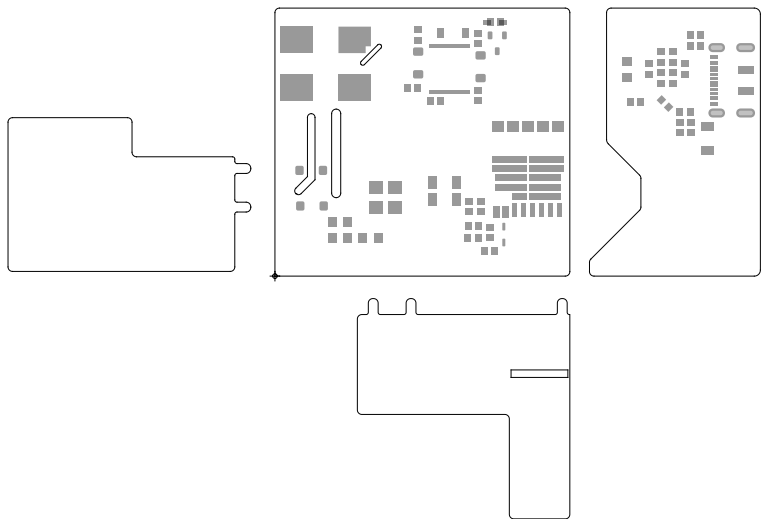
CY-SD1124A REV03 PRIMARY SILKSCREEN

ART FILM - SSM



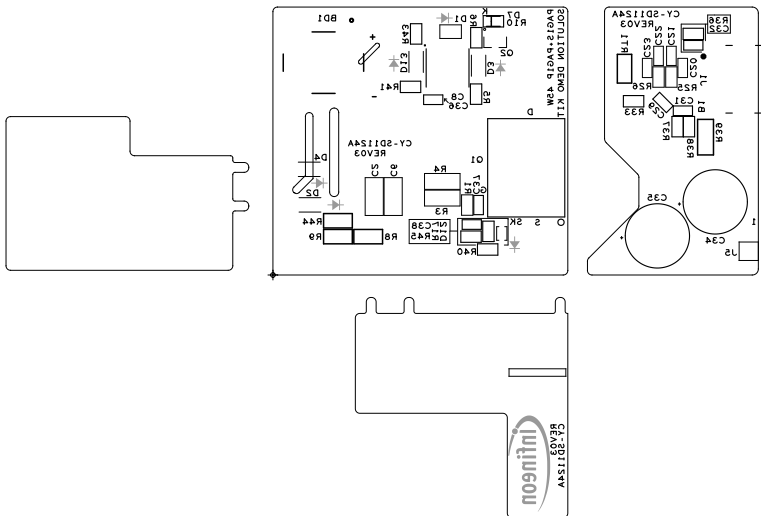
CY-2D11S4A REV03 SECONDARY SOLDER MASK

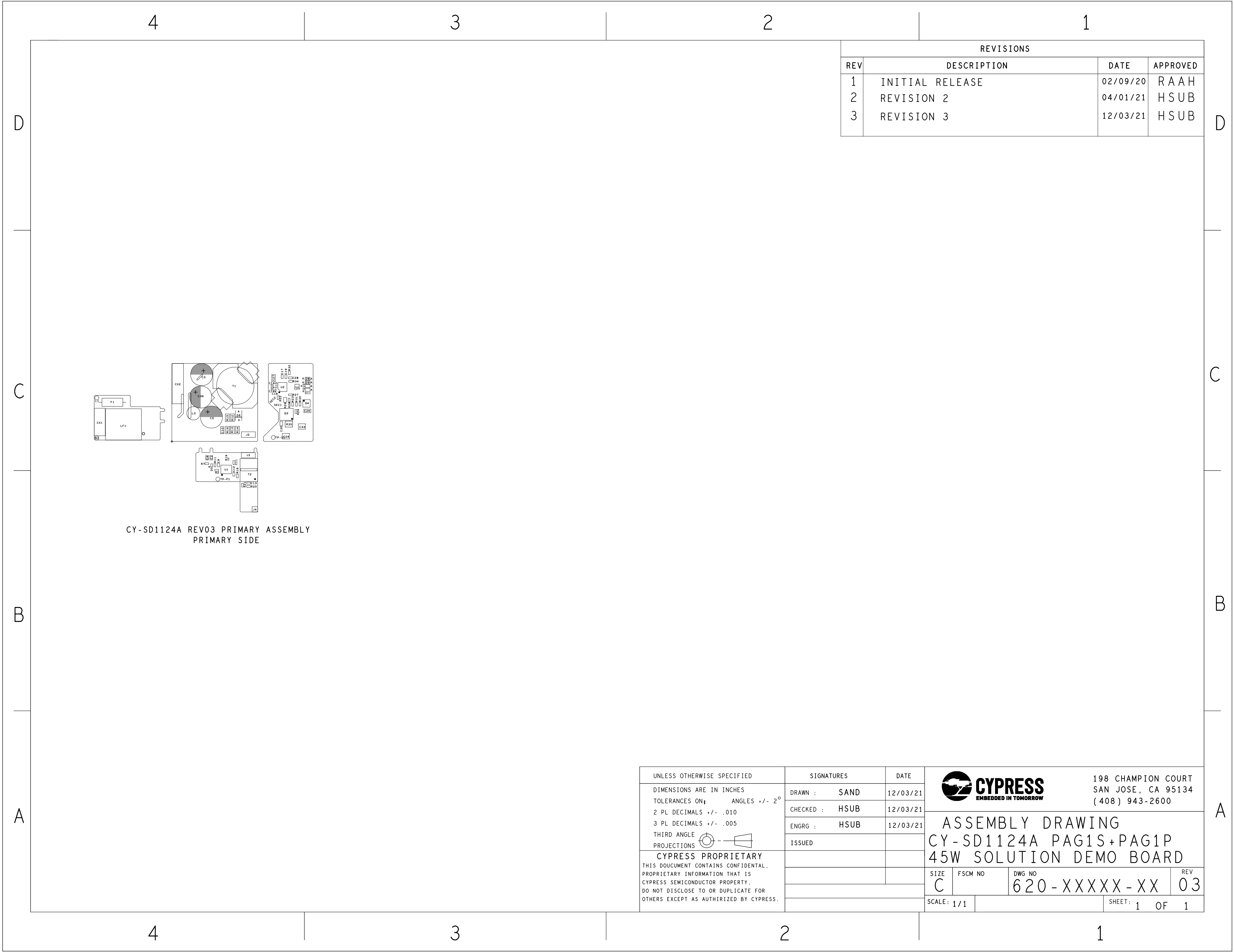
ART FILM - SSM



CY-2D11S4A REV03 SECONDARY SOLDERPASTE


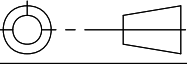
CY-2D11S4A REV03 SECONDARY SILKSCREEN





CY-SD1124A REV03 PRIMARY ASSEMBLY
PRIMARY SIDE

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THIRD ANGLE PROJECTIONS 					
CYPRESS PROPRIETARY				SIZE	FSCM NO
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				DWG NO	REV
				620-XXXXXX-XX	03
				SCALE: 1/1	SHEET: 1 OF 1

